



**Schedule of Scope to Certificate of Conformity**  
**Approved Component - Capability**  
IECQ Certificate No.: IECQ-C BSI 14.0052  
CB Certificate No.: 029/ICA

Schedule Number: IECQ-C BSI 14.0052-S Rev No.: 4 Revision Date: 2021/11/02 Page 1 of 1

**Test Reports:**

7293042	4 March 2009
38590	25 March 2009
8011	27 Sept 2021

**Board Types** Multilayer boards with blind and/or buried vias (Type 4) IPC 6012E Class 3  
Multilayer boards without blind or buried vias (Type 3)  
Double-sided boards (Type 2)  
Single-sided boards (Type 1)

**Base Materials:** Epoxide woven glass IPC 4101/26  
(21, 24, 98, 99, 101, 126)

**Board Size:** 405 mm x 280 mm (Type 3 & 4)  
500 mm x 360 mm (Type 1 & 2)

**Conductors:** Minimum width: 0.1 mm ± 0.05mm 12 µm foil  
Minimum spacing: 0.1 mm ± 0.05mm 18 µm foil

**Number of Layers:** 16 (Class 2), 12 (Class 3) Maximum

**Plated-through hole Diameter:** 0.5 mm minimum drilled

**Aspect Ratio:** 6.4 : 1 (Class 2), 4.6 : 1 (Class 3) Maximum

**Finishes:** 63:37 Tin/Lead Hot Air Solder Level  
Electroless Nickel / Immersion Gold  
Electrolytic Nickel and Gold  
Organic Solderability Preservative  
Immersion Silver  
Photoimageable solder resist  
IR Cured Notation Ink

**Additional:** Bonded Heatplanes: Anodized Aluminium  
Nickel Plated Copper

Note: It may not be possible to achieve the limits of the capability in combination. Such combinations are determined by the agreed customer detail specification for the PCB ordered.

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